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1 Navy Case No. 76632

2
3 OMNIDIRECTIONAL ULTRASONIC MICROPROBE HYDROPHONE

4
5 STATEMENT OF GOVERNMENT INTEREST

6 The invention described herein may be manufactured and used
7 by or for the Government of the United States of America for
8 governmental purposes without the payment of any royalties
9 thereon or therefor.

10
11 BACKGROUND OF THE INVENTION

12 (1) Field of the Invention

13 The present invention is directed to an omnidirectional
14 ultrasonic microprobe hydrophone for medical imaging and
15 therapeutic applications. Still further, the present invention
16 is directed to an omnidirectional ultrasonic microprobe
17 hydrophone for use in underwater mine detection, explosive shock
18 testing, and high-wavenumber measurements.

19 (2) Description of The Prior Art

20 It is known to utilize thin-film polyvinylidene fluoride
21 (PVDF) membrane hydrophones with 1mm^2 electrode areas to probe
22 the fields of focused projectors, but the electrode area is too
23 large for accurate measurements in the neighborhood of a focus.
24 Use of a smaller electrode size is impractical because the

1 capacitance would become too small to drive the preamplifier,
2 which must be located at some distance from the sensing element
3 to ensure reflection-free dosimetry measurements. The membrane
4 probes also require frequent replacement when used to measure
5 levels near the focus of ultrasonic lithotripsy projectors.
6 Because they are essentially hand made, they are costly.

7 The traditional blast gage, made of tourmaline crystal, is
8 used for measuring the amplitudes of explosive shock waves. The
9 tourmaline crystal is highly directional since making it small
10 enough for omnidirectionality would severely reduce the
11 capacitance and sensitivity of the gage. When precisely oriented
12 (a time-consuming process) so as to respond accurately to the
13 sharp rise of the shock front, the gage "rings" at its resonance
14 frequency (typically several MHz), because the shock front is
15 rich in frequency components in the neighborhood of the
16 resonance. Therefore, blast gages are usually placed edge-on
17 with respect to the incoming shock wave, a procedure that limits
18 the frequency response and rise time that can be accurately
19 measured.

20 In order to measure the high-wavenumber pressure fields
21 associated with turbulent flow, the probe size must be smaller
22 than the reciprocal of a characteristic wavenumber of the field,
23 i.e., smaller than the mean flow velocity divided by the
24 frequency. End-capped lead zirconate titanate (PZT) cylinders

1 are often used for such measurements, but they cannot be made
2 smaller than 1mm, limiting the maximum wavenumber to about 500
3 cycles/meter. The maximum frequency for such measurements is
4 about 5 kHz for a 10 m/sec (20 Knot) flow velocity.

5 A number of different microprobe devices are known in the
6 art. However, these known devices do not incorporate the
7 omnidirectional capabilities of the inventive device and include:

8 U.S. Patent No. 4,316,115 to Wilson et al. as disclosing a
9 Polymeric Piezoelectric Microprobe With Damper; U.S. Patent No.
10 4,433,400 to DeReggi et al. as disclosing an Acoustically
11 Transparent Hydrophone Probe; U.S. Patent No. 4,422,003 to Safari
12 et al. as disclosing Perforated PZT Polymer Composites; U.S.
13 Patent No. 4,672,591 to Breimesser et al. as disclosing an
14 Ultrasonic Transducer; U.S. Patent No. 4,841,494 to Banno as
15 disclosing an Underwater Piezoelectric Arrangement; U.S. Patent
16 No. 5,072,426 to Schafer et al. as disclosing a Self-Monitoring
17 Shock Wave Hydrophone; U.S. Patent No. 5,137,776 to Kahn as
18 disclosing a Metal-Coated, Ordered Void Piezoelectric Ceramic
19 Material; U.S. Patent No. 5,209,119 to Polla et al. as
20 disclosing a Microdevice for Sensing a Force; and U.S. Patent No.
21 5,367,500 to Ng as disclosing a Transducer Structure.

1 Further scope of applicability of the present invention will
2 become apparent from the detailed description given hereinafter.
3 However, it should be understood that the detailed description
4 and specific examples, while indicating preferred embodiments of
5 the invention, are given by way of illustration only, since
6 various changes and modifications within the spirit and scope of
7 the invention will become apparent to those skilled in the art
8 from this detailed description.

9
10 BRIEF DESCRIPTION OF THE DRAWINGS

11 The present invention will become more fully understood from
12 the detailed description given herein below and the accompanying
13 drawings which are given by way of illustration only, and thus
14 are not limitative of the present invention and wherein
15 corresponding reference characters indicate corresponding parts
16 throughout the several views of the drawings and wherein:

17 FIG. 1 is an overall illustration of the microprobe of the
18 present invention;

19 FIG. 2A is a top plan schematic view of the microprobe
20 hydrophone according to a preferred embodiment of the present
21 invention;

22 FIG. 2B is a side schematic view of the microprobe
23 hydrophone shown in FIG. 2A;

1 FIG. 3A is an enlarged top plan view of a pressure sensing
2 element in the microprobe hydrophone shown in FIGS. 2A and 2B;

3 FIG. 3B is an enlarged side view of the pressure sensing
4 element shown in FIG. 3A;

5 FIGS. 4A and 4B are top plan and side views, respectively,
6 of the microprobe of the present invention packaged with a custom
7 preamplifier;

8 FIG. 5 is an enlarged side view illustrating columnar voids
9 formed in a sensing element of the microprobe hydrophone of FIGS.
10 2A and 2B;

11 FIG. 6A is a top plan view of a microprobe hydrophone
12 according to a second preferred embodiment of the present
13 invention;

14 FIG. 6B is a cross-sectional view through an outer electrode
15 of the embodiment shown in FIG. 6A;

16 FIG. 6C is a cross-sectional view through an inner electrode
17 of the embodiment shown in FIG. 6A;

18 FIG. 7 illustrates a first placement of sensing elements
19 according to either of the first or second preferred embodiments
20 of the present invention;

21 FIG. 8 illustrates a line array of microprobes; and

22 FIG. 9 illustrates a planar array of microprobes.

1 example, the pressure sensing element 10 has an electroded area
2 of approximately 35 μm square and a thickness of 1 μm , as shown.
3 The thickness of the substrate material 12 is approximately 25
4 μm . With these dimensions and a void fraction of 10 percent, the
5 capacitance of the pressure sensing elements 10 (connected in
6 parallel) is about 30 pF, and the open circuit sensitivity is
7 approximately -273 dB//1V/ μPa .

8 With the size of the pressure sensing elements 10 at 35 μm ,
9 it can be ensured that the response will be omnidirectional
10 within +/- 1 dB at 10 MHz in water. The length of the probe,
11 shown as 80 mm in FIG. 2B, is dictated by the maximum pulse
12 length to be received. The 80 mm microprobe length is sufficient
13 to receive a 5 cycle tone burst at 0.1 MHz without interference
14 from echoes due to reflections from the microprobe supporting
15 structure. The probe 50 is tapered, as generally shown in FIG.
16 1, so that the support end, composed of wire bonds 18 and 18a, is
17 wide enough for convenience in handling and to serve as a base
18 for the wire bonds 18 and 18a. The support end of the substrate
19 conductor 12, shown in FIGS. 2A and 2B with typical dimensions of
20 300 μm wide by 25 μm thick, forms a convenient gluing surface for
21 attachment to the supporting structure and preamplifier.

22 By way of example, FIGS. 4A and 4B are directed to a
23 mounting configuration for the microprobe hydrophone, wherein the
24 microprobe is attached to a custom preamplifier (chip-on-board

1 version). As shown in FIG. 4A, the microprobe 50 is mounted to a
2 printed circuit board 52, made of ceramic, epoxy or the like.
3 The printed circuit board 52 includes at least one chip capacitor
4 58 mounted thereon, a preamplifier integrated circuit 54 mounted
5 thereon and a plurality of lead wires 56 extending from the
6 integrated circuit. The integrated circuit 54 may consist of a
7 monolithic, low-noise preamplifier for piezoelectric sensors such
8 as that disclosed by Straw in U.S. Patent No. 5,339,285.

9 Also provided on the printed circuit board 52 is a plurality
10 of wire connections 60. As shown in FIG. 4B, a lower surface of
11 the printed circuit board 52 includes a mounting plate 62. A
12 combination of the printed circuit board 52 including all
13 elements mounted thereon as described above is encapsulated by a
14 conformal coating 64 and the microprobe 50 is individually
15 encapsulated by an acoustically transparent sealant 66.

16 The structure of the columnar voids 30 is schematically
17 illustrated in FIG. 5. More specifically, the plurality of
18 columnar voids 30 is produced as a result of constrained
19 sintering at the interface between the piezoceramic material 10
20 and the substrate material 12. By proper choice of materials,
21 process temperatures, and piezoceramic thickness, the columnar
22 voids can be prevented from propagating to the outer surface of
23 piezoceramic material 10. Subsequent deposition of the outer

1 conductor 16 can be done on the flat, nonporous outer surface of
2 the piezoceramic element 10.

3 The electrical impedance presented to the sensing elements
4 10 is that of a shunt capacitance and a series resistance formed
5 by the conductors 12 and 16 and the intervening dielectric
6 material 14. The 1 μm thickness of the sensing elements 10
7 ensures that the element capacitance will be larger than the
8 shunt capacitance. The dielectric material 14 should have a
9 small dielectric constant (preferably less than 5) so as to
10 minimize the shunt capacitance. With typical values of 1 μm for
11 the thickness of the dielectric material 14 and 5 μm for the
12 width of outer conductor 16, the shunt capacitance is estimated
13 to be about 35 pF. If the preamplifier capacitance is taken to
14 be 15 pF, the sensitivity of the microprobe will be
15 $-273-20\log(30/(30+35+15)) = -282\text{dB//}1\text{V}/\mu\text{Pa}$. In other words,
16 there is a coupling loss of 9 dB due to the nonzero shunt
17 capacitance of the leads and the preamplifier. To ensure that
18 the series resistance of conducting layers 16 is small compared
19 to the reactance of the shunt capacitance, the thickness of
20 conducting layers 16, if they are copper, must be at least 0.5 μm
21 over the 80 mm length of the probe. Then, the high-frequency RC-
22 rolloff in response will be less than 1 dB at 10 MHz.

23 For use in liquid media, such as water, and in humid or
24 corrosive gaseous media, acoustically transparent sealant 66 is

1 necessary to protect the microprobe. Parylene can be used,
2 similar to the standard practice with printed circuit boards.
3 Alternatively, the microprobe can be dipped in polyurethane or
4 another elastomeric material as a final step in manufacture.

5 The presence of the plurality of columnar voids 30 within
6 the PZT elements 10 ensures that the lateral stresses, such as
7 those in the plane of a sensing element 10 are small compared to
8 the stress perpendicular to the plane of the element 10. Thus,
9 the PZT piezoceramic material operates in the so-called 3,3 mode,
10 wherein the only nonzero stress component is in the polarization
11 direction. The 3,3 mode is the preferred mode for PZT, with a
12 figure of merit, $FOM = \text{sensitivity} + 10 \log (\text{capacitance})$, that
13 is 20 dB higher than for operation in the hydrostatic mode,
14 wherein all three stress components would be equal. The FOM is
15 12 dB higher than that of PVDF. In other words, the optimum
16 (i.e., maximum obtainable) signal-to-noise ratio would be 12 dB
17 less for an equal volume of PVDF.

18 Materials that are usually considered suitable for the
19 hydrostatic mode of operation, such as lead metaniobate,
20 tourmaline, and PVDF, all have permittivities that are a small
21 percentage of that of PZT, and for hydrophones as small as $35 \mu\text{m}$
22 $\times 35 \mu\text{m}$, PZT's high permittivity gives it an important advantage
23 over hydrostatic-mode hydrophone materials. The resulting high
24 probe capacitance allows the preamplifier to be placed remotely

1 from the sensing elements 10, so that ultrasonic measurements
2 free of spurious reflections from the preamplifier can be
3 performed. This also permits the use of commercial preamplifiers
4 that can be mounted on the supporting structure 62, without the
5 necessity of manufacturing the preamplifier on the same substrate
6 as the sensing elements. A number of manufacturing constraints,
7 such as processing temperature requirements, are thereby
8 eliminated, and the substrate material does not need to be a
9 semiconductor. Thus, the substrate can be a metallic foil, which
10 forms one of the electrodes of the microprobe and eliminates the
11 need to deposit that conductor during manufacture.

12 The long (80 mm), thin (25 μm) substrate conductor 12 acts
13 as an isolator for mechanical vibrations that originate in the
14 supporting structure or mounting plate 62, such as the structural
15 response to an incoming acoustic shock wave, because the
16 mechanical resonance frequencies of the substrate conductor 12
17 lie well below the 0.1-10 MHz band of interest. On the other
18 hand, the fundamental resonance of sensor elements 10 occurs at
19 about 1 GHz, well above the frequency band of interest. Thus,
20 undesired, spurious resonances within the 0.1-10 MHz band are not
21 expected to occur.

22 Two symmetrically placed sensor elements 10, as shown in
23 FIGS. 2A, 2B, 3A, and 3B form an acceleration cancelling
24 hydrophone, because they respond oppositely to acceleration

1 components perpendicular to the sensor elements 10 and not at all
2 to accelerations that lie within the plane of sensor elements 10.
3 The symmetry of sensor elements 10 also helps to ensure the
4 omnidirectionality of the beam pattern. If only one element were
5 used, the back side of substrate conductor 12 would act as a
6 baffle to acoustic waves from that direction.

7 Commonly used ultrasonic probes are hand-built, resulting in
8 high production costs per unit. Since the proposed device
9 geometry is relatively simple, consisting of layers of
10 piezoelectric material 10, metal electrodes 12 and 16, and
11 insulating layers 14, the methods used in fabrication are similar
12 to those for the fabrication of integrated circuits, including
13 sol-gel casting, photolithography, and chemical vapor deposition.
14 Economies of scale are possible, because several hundred
15 microprobes can be constructed on each disk of substrate material
16 12.

17 It is expected that the disclosed device will be better able
18 to withstand multiple high-level shock pulses than PVDF membrane
19 probes, so that less frequent replacement, due to electrode
20 delamination, will be required. Bonding a metal electrode to
21 PVDF is difficult because of the presence of fluorine, whereas
22 the PZT-to-metal bonds will be stronger because of more favorable
23 chemistry.

1 It should be understood that the columnar voids 30 must be
2 internal to piezoceramic sensor elements 10, and the controlled
3 sintering process described above is the most promising and
4 simplest method of production. However, other methods, such as
5 photolithic/photoresist techniques, may be used to produce the
6 voided regions. In that case, one would need to deposit thin
7 cover layers of PZT to close the outer ends of the voids,
8 ensuring that the newly deposited material does not fill the
9 voids. The thin cover layers of PZT would be approximately 0.1
10 μm in thickness.

11 Another possible approach to this problem is to deposit
12 volatile material in the spaces to be voided using material that
13 vaporizes during the firing of the PZT, thereby forming the
14 voids.

15 As illustrated by the embodiment of FIG. 6A, the substrate
16 material does not have to be an electrical conductor. Instead, a
17 microprobe hydrophone is shown wherein the substrate material 36
18 is an insulator such as aluminum oxide, on which a metallic
19 electrode 38 has been deposited. This configuration has the
20 advantage that the shunt capacitance of the leads can be made
21 significantly less than that of the sensing elements 10,
22 resulting in a decrease in coupling loss, and an increase in
23 sensitivity of about 3 dB. FIG. 6B shows a cross-sectional view
24 through the outer electrode 16, an insulator 14 and conducting

1 member 22, that is similar to the construction described above.
2 The insulating layer 14 is largely unnecessary here and it serves
3 only to maintain a flat surface for deposition of electrode 16.

4 FIG. 6C shows a cross-sectional view through the inner
5 electrode 38 and inner conducting member 40. Also shown in FIGS.
6 6A and 6C are the wire bonds 18 and 18a and wire leads 20 and 20a
7 at the support end of the microprobe.

8 The devices described so far entail sensing elements 10 at
9 the small end of a substrate conductor or insulator. To provide
10 greater control over the positioning of the microprobe, two
11 support ends, rather than one, may be utilized. In other words,
12 the sensing elements 10 can be placed as shown in FIG. 7 at the
13 center of a filamentary substrate 46 that is 25 μm thick and 300
14 μm wide at its support ends.

15 Alternatively, several pairs of elements 10 could be
16 deposited on a single substrate filament 46, forming a line
17 array, as shown in FIG. 8. By using a matrix of such filamentary
18 substrates 46, one can form a planar array of microprobe
19 hydrophones, as is illustrated in FIG. 9.

20 The sensing elements 10 can be wired in series to achieve a
21 higher impedance, if desired, to match the noise impedance of the
22 preamplifier. The microprobe can be used with various
23 commercially available preamplifiers with various supporting
24 structures. One alternative supporting structure could be a flat

1 cable upon which the preamplifier and the support end (the wide
2 end) of the microprobe are attached.

3 Finally, although the primary purpose of the invention is to
4 detect ultrasonic signals regardless of their direction or
5 bandwidth up to 10 MHz, a secondary purpose is to detect pressure
6 disturbances having wavenumbers as high as 14,000 cycles/meter.
7 The primary acoustic medium is assumed to be water, but the
8 device will be useful in other fluid media as well. Because of
9 the small size of the microprobe, it would easily fit into a
10 catheter for use as a passive acoustic intra-arterial receiver.

11 The invention being thus described, it will be obvious that
12 the same may be varied in many ways. Such variations are not to
13 be regarded as a departure from the spirit and scope of the
14 invention.

1 Navy Case No. 76632

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3

OMNIDIRECTIONAL ULTRASONIC MICROPROBE HYDROPHONE

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ABSTRACT OF THE DISCLOSURE

6 An omnidirectional ultrasonic microprobe hydrophone is
7 disclosed. Applications include underwater mine detection,
8 explosive shock testing, high wave number measurements, medical
9 imaging, and therapeutic systems. The apparatus includes at
10 least two lead zirconate titanate (PZT) pressure sensing elements
11 having a plurality of columnar voids formed therein. The
12 pressure sensing elements are deposited on a metallic or
13 nonmetallic substrate which provides mechanical support for the
14 microprobe hydrophone. Electrical connection to the pressure
15 sensing elements is made by deposition of conductors and
16 insulators on the substrate material. Wire bonds are used to
17 attach wire leads for connection to a supporting structure
18 containing a preamplifier. Line arrays and planar arrays of
19 microprobe hydrophone elements are also disclosed.

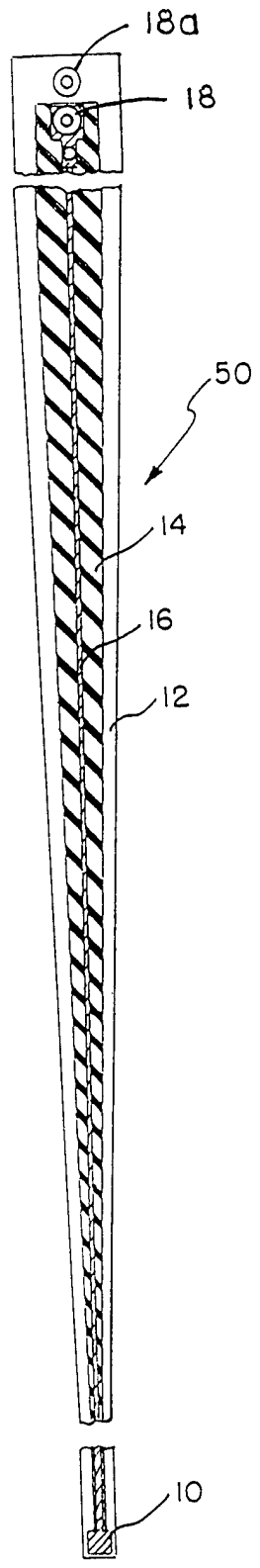


FIG. 1

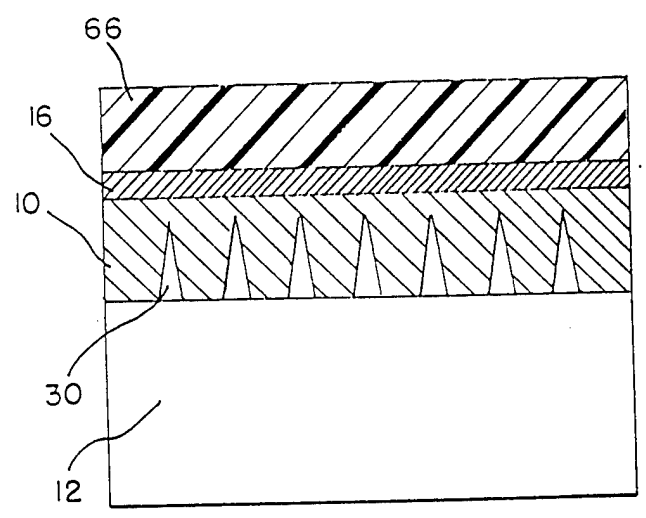


FIG. 5

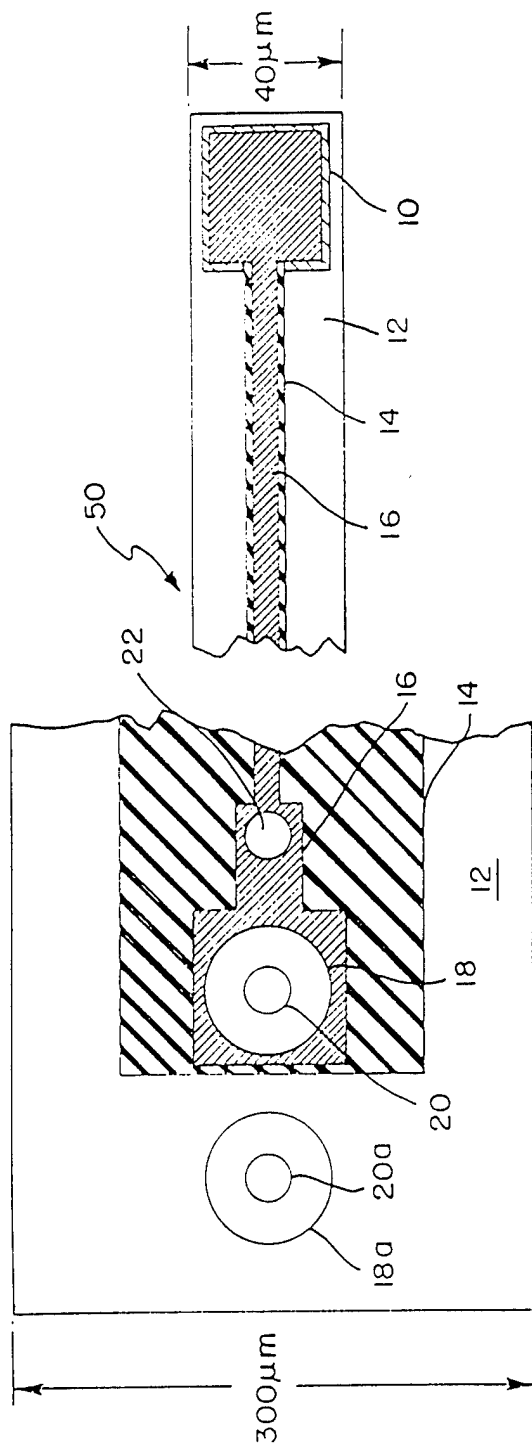
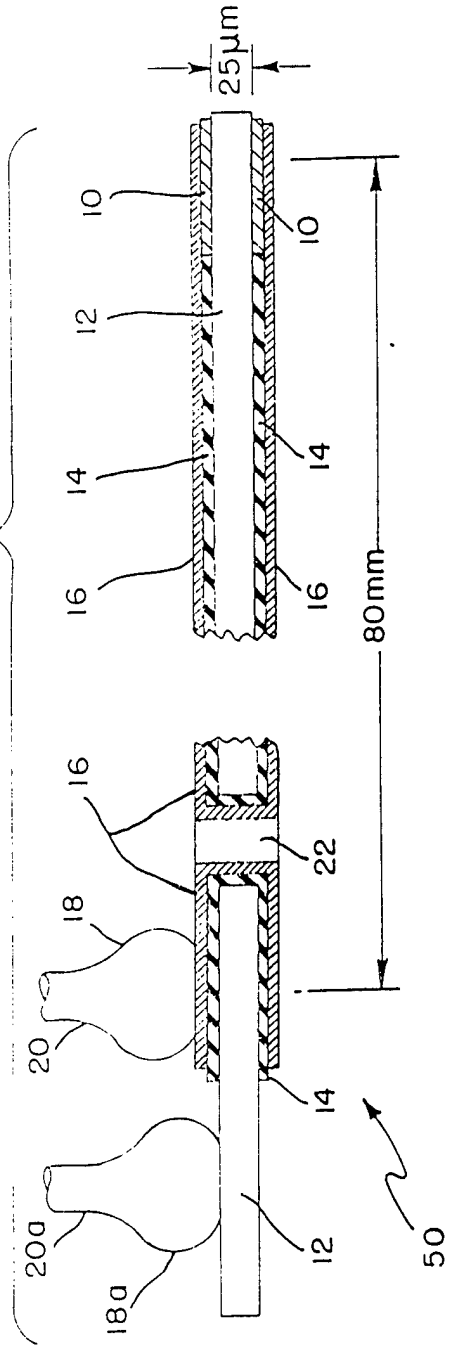


FIG 2A · FIG 2B



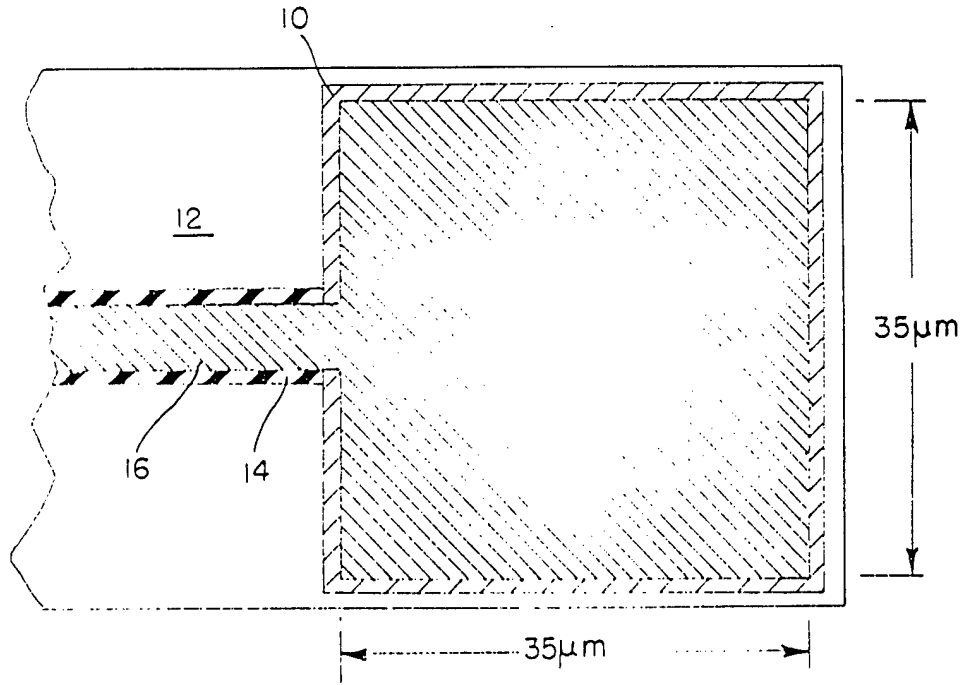


FIG. 3A

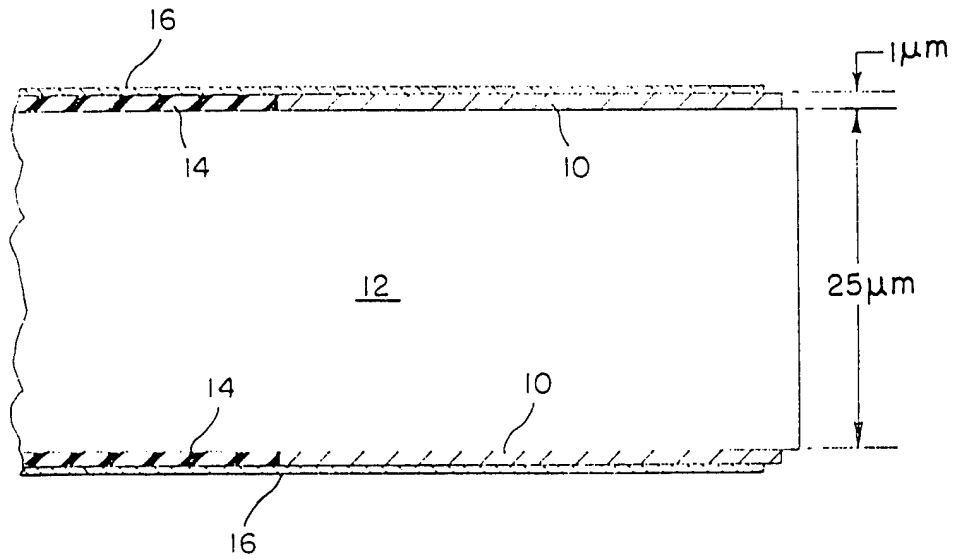


FIG. 3B

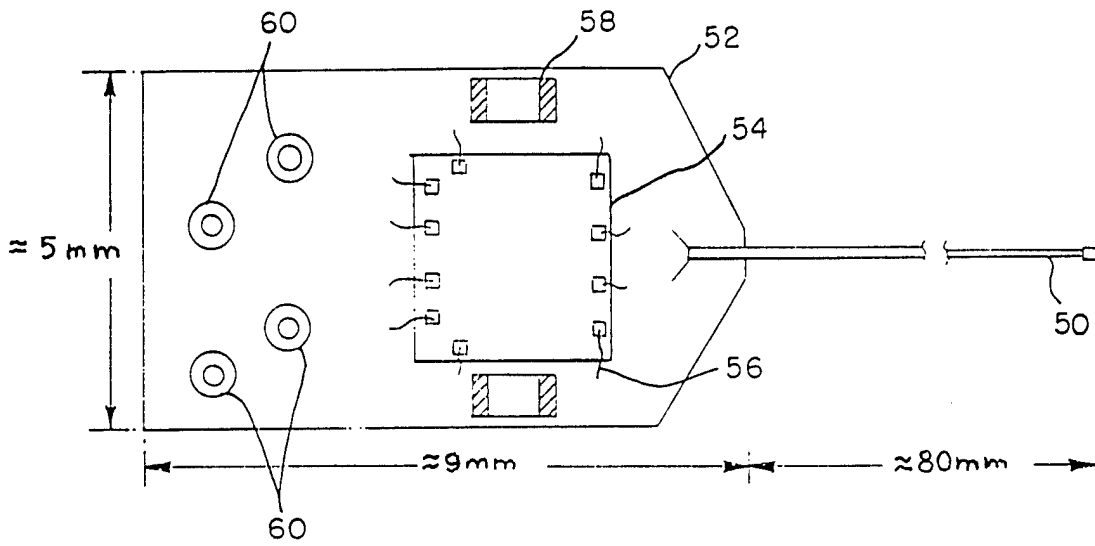


FIG. 4A

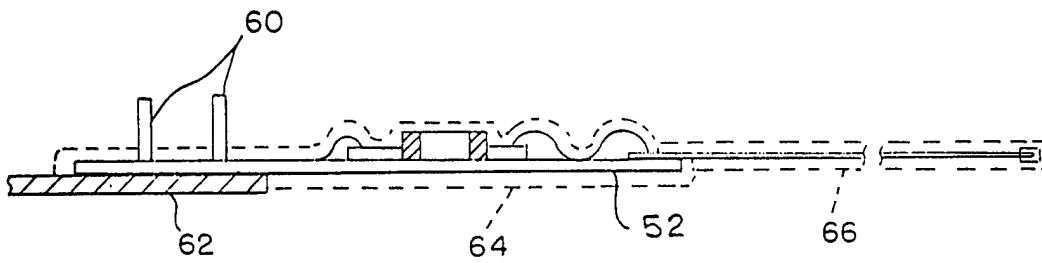


FIG. 4B

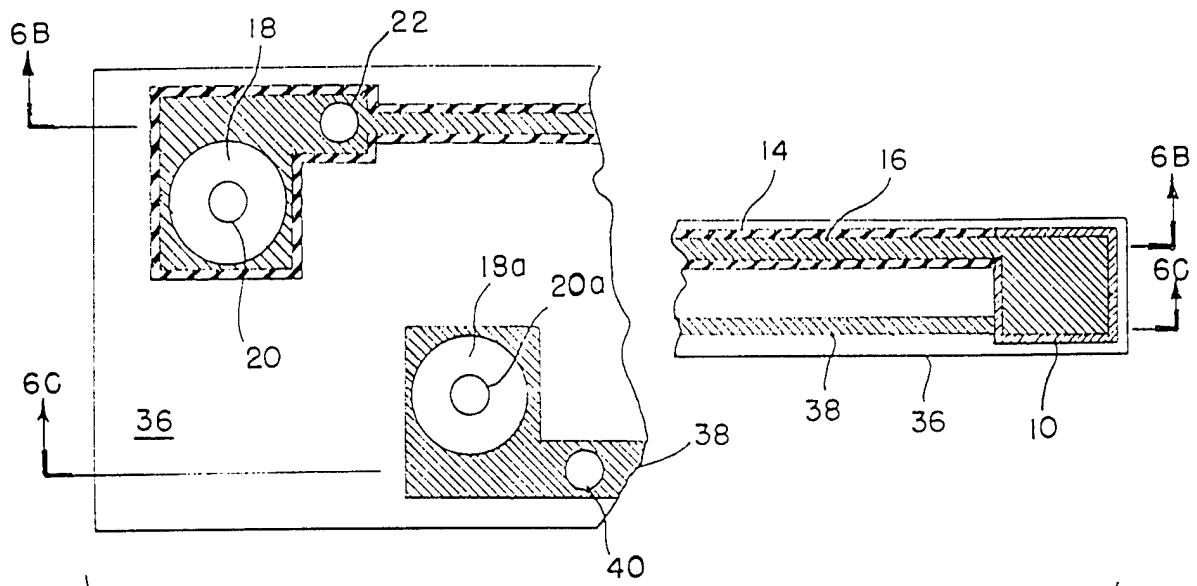


FIG. 6A

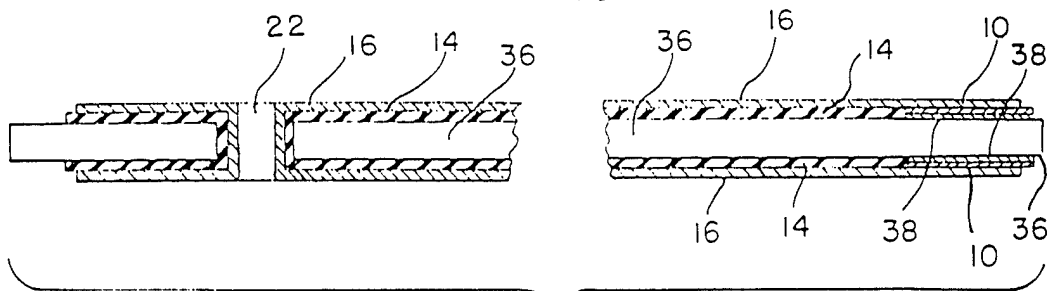


FIG. 6B

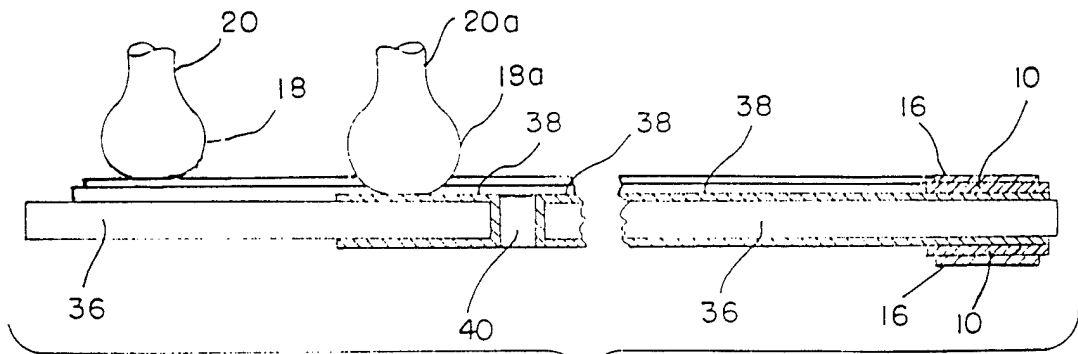


FIG. 6C

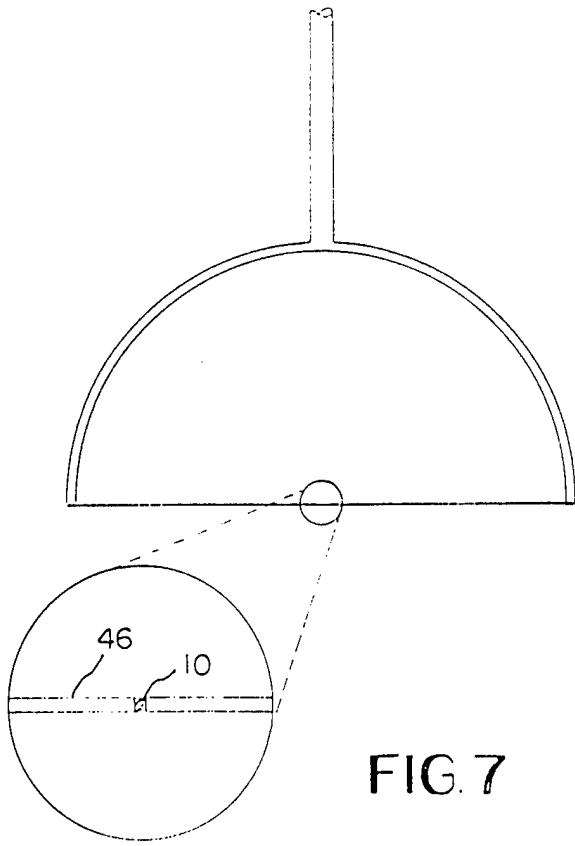


FIG. 7

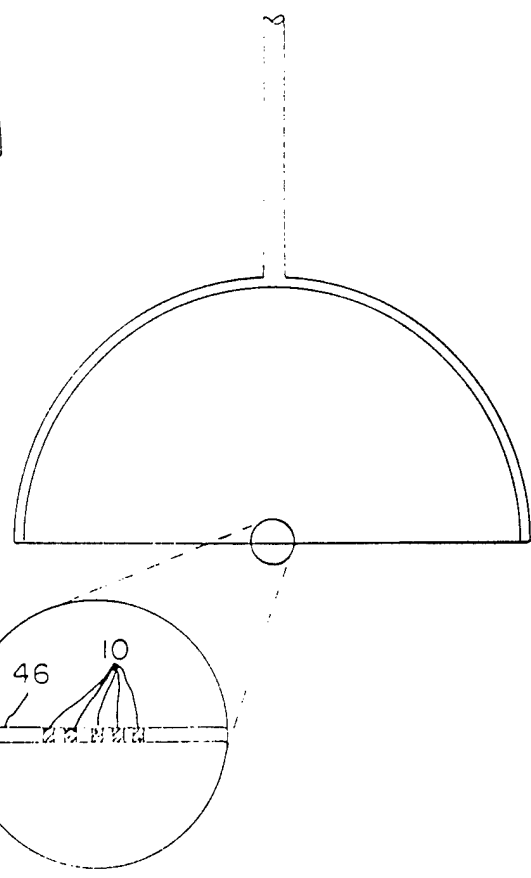


FIG. 8

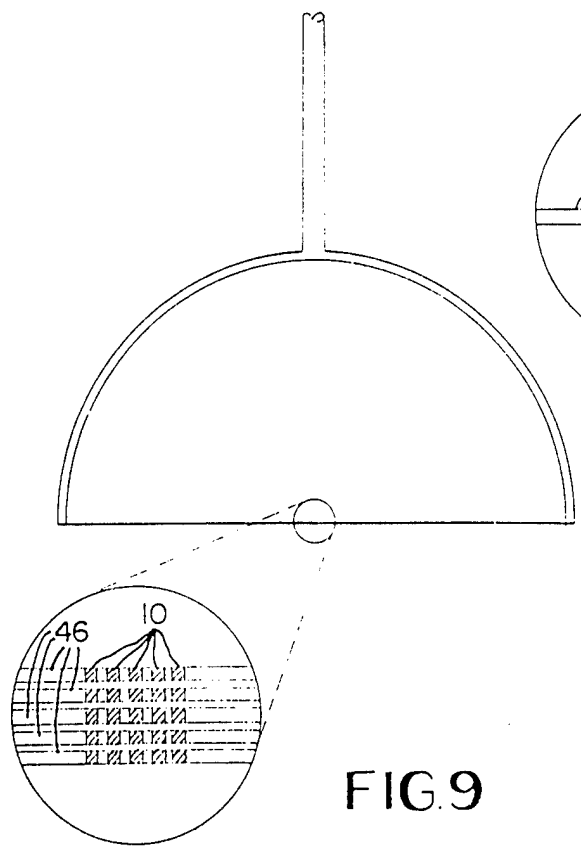


FIG. 9